

Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

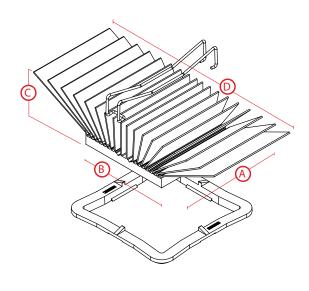
ATS PART # ATS-51190K-C2-R0

Features & Benefits

- » maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- » Comes preassembled with high performance, phase changing, thermal interface material

Thermal Performance

» Designed for low profile components from 1.5 to 2.99mm





*Image above is for illustration purposes only.

AIR VELOCITY				THERMAL RESISTANCE		
	FT/MIN M/S		°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)		
	200	1	.0	10.1	7.9	
	300	1	.5	8.3		
	400	2	2.0	7.2		
500		2.5		6.4		
600		3	5.0	5.9		
	700		5.5	5.5		
800		4	.0	5.1		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
19 mm	19 mm	14.5 mm	34.8 mm	SAINT-GOBAIN C1100F	BLACK- ANODIZED

NOTES:

- 1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
- ATS-51190K-C1-R0 is a subsitute item available utilizing an equivalent phase change material (Chomerics T766).
- Thermal performance data are provided for reference only. Actual performance may vary
- by application.
 ATS reserves the right to update or change its products without notice to improve the design or performance.
- 5) Optional maxiGRIP[™] Installation/Removal Tool Set P/N: MGT190
- 6) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).